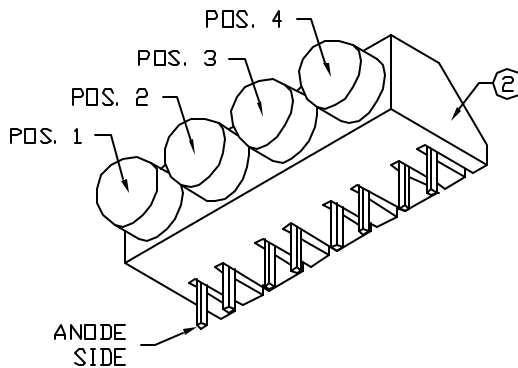
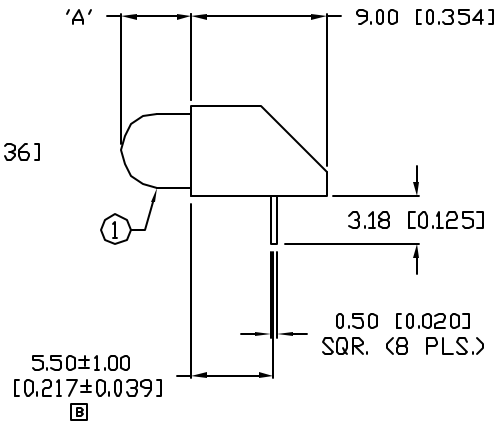
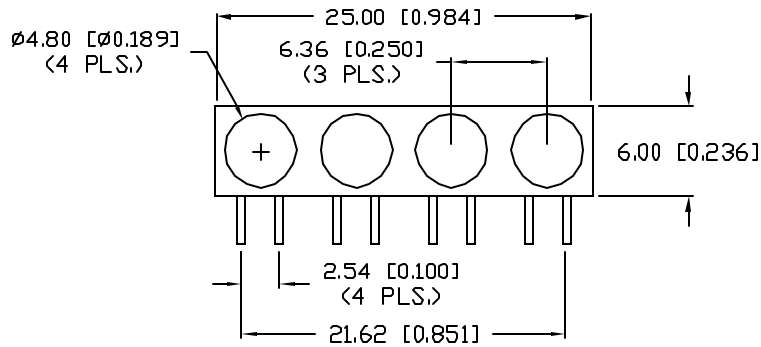


UNCONTROLLED DOCUMENT

PART NUMBER
SSF-LXH400YD(-1)

REV.
D

REV.	E.C.N. NUMBER AND REVISION COMMENTS	DATE
A	CHG'D LEAD LENGTH./CHGD DIM A.	11.3.93
B	E.C.N. #10303.	2.3.97
C	E.C.N. #10314.	2.27.97
D	E.C.N. #10BRDR. & REDRAWN.	5.15.01



Ⓜ DIM 'A'

WITH NO SUFFIX: 2.50±0.50 [0.126±0.020]
WITH -1 SUFFIX: 4.70±0.50 [0.187±0.020]

ELECTRO-OPTICAL CHARACTERISTICS $T_A=25^\circ\text{C}$ $I_f=20\text{mA}$

PARAMETER	MIN	TYP	MAX	UNITS	TEST COND
PEAK WAVELENGTH		585		nm	
FORWARD VOLTAGE		2.1	2.5	V _f	
REVERSE VOLTAGE	5.0			V _r	I _f =100μA
AXIAL INTENSITY		20		mcad	I _f =20mA
VIEWING ANGLE		60		2x theta	
EMITTED COLOR:	YELLOW				
EPOXY LENS FINISH:	YELLOW DIFFUSED				

LIMITS OF SAFE OPERATION AT 25°C PER DIE

PARAMETER	MAX	UNITS
PEAK FORWARD CURRENT*	150	mA
STEADY CURRENT	30	mA
POWER DISSIPATION	105	mW
DERATE FROM 25°C	-1.2	mW/°C
OPERATING, STORAGE TEMP.	-40 TO +85	°C
SOLDERING TEMP.	+260	°C
2.0mm FROM BODY		3 SEC. MAX

* $t < 10\mu\text{s}$

NOTES:

- NO SUFFIX: SSL-LX507F3YD. (4 PCS.)
(-1) SUFFIX: SSL-LX509F3YD. (4 PCS.)
- SSH-LXH400 HOLDER, BLACK.
- PACKAGE PARTS IN ANTISTATIC TUBES.

*UNLESS OTHERWISE SPECIFIED TOLERANCES PER DECIMAL PRECISION ARE: X=±1 (±0.039), X.X=±0.5 (±0.020), X.XX=±0.25 (±0.010), X.XXX=±0.127 (±0.005). LEAD SIZE=±0.05 (±0.002), LEAD LENGTH=±0.75 (±0.030). MIN= ^{+0.00}-0.00 DECIMAL PRECISION MAX.= ^{+0.00}-0.00 DECIMAL PRECISION

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REV.	PART NUMBER
D	SSF-LXH400YD(-1)

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T-5mm (T-1 3/4) 4 POSITION FAULT INDICATOR.
585nm YELLOW LED, YELLOW DIFFUSED LENS.

RELIABILITY NOTE
OUR MANY YEARS OF EXPERIENCE DATA ACCUMULATION INDICATE THAT SOLDER HEAT IS A MAJOR CAUSE OF EARLY AND FUTURE FAILURE. PLEASE PAY ATTENTION TO YOUR SOLDERING PROCESS.

DRAWN BY: GT	CHECKED BY:	APPROVED BY:	DATE: 5.26.92
			PAGE: 1 OF 1
			SCALE: N/A